Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1409	(takashi near2 yokoyama or koji near2 yoshihara or toshiaki near2 saishoji or kozo near2 nakamura or ryota near2 suewa).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/08 13:43
L2	111	(takashi near2 yokoyama or koji near2 yoshihara or toshiaki near2 saishoji or kozo near2 nakamura or ryota near2 suewa).in. and (si or silicon) near6 crystal\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/08 13:44
L3	47	(takashi near2 yokoyama or koji near2 yoshihara or toshiaki near2 saishoji or kozo near2 nakamura or ryota near2 suewa).in. and (si or silicon) near6 crystal\$6 and void	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/08 13:44
S1	37	czochralski and convex near5 melt near5 interface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/21 18:01
S2	14	czochralski and convex near5 melt near5 interface and magnet\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/21 18:13
S3	2	"20060016387".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/21 18:14
S4	56	czochralski and crystal near5 cooler	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/21 18:16
S5	5	"20030154907"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2007/05/21 18:16
S6	7	"20020144641".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/21 18:18

		LAST Scarci	,			
S7	10	(si or silicon) near10 wafer and ("no" or free) near10 (osf or oisf or oxidat\$5 near4 stack\$5) and void near5 density	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/21 18:33
S8	310	(si or silicon) near10 wafer and void near4 density	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/21 18:34
S9	86	(si or silicon) near10 wafer and void near4 density and void near4 size	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/21 18:34
S10	7	(si or silicon) near10 wafer same void near4 density same void near4 size	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/21 18:40
S11	35	"0171069"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/21 18:44
S12	2	"200171069"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/21 18:41
S13	2	"5935320".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/21 18:44
S14	125	czochralski same carbon near5 (dop\$5 or concentrat\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/21 18:45
S15	72	czochralski same carbon near5 (dop\$5 or concentrat\$5) and @py<"2003"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/21 18:57
S16	42	czochralski same carbon near5 (dop\$5 or concentrat\$5) same (silicon or si) and @py<"2003"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/21 19:02

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S17	33	carbon near10 "cm.sup.3" near10 (ppm or ppma)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/21 19:00
S18	0	czochralski same carbon near5 (dop\$5 or concentrat\$5) near5 less same (silicon or si) and @py<"2003"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/21 19:03
S19	29	czochralski and carbon near5 (dop\$5 or concentrat\$5) near5 less same (silicon or si) and @py<"2003"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/21 19:03
S20	24	convex and czochralski and cooler	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/07 15:34
S21	1	"6869478".pn. and void\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/07 15:42
S22	159	(si or silicon) near5 wafer same (heat near2 treat\$6 or anneal\$6) near16 (osf or oisf or stacking near2 fault)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/07 15:43
S23	3	(si or silicon) near5 wafer same (heat near2 treat\$6 or anneal\$6) near16 (osf or oisf or stacking near2 fault) near10 (non\$10xidat\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/07 15:45
S24	20	(si or silicon) near5 wafer same (heat near2 treat\$6 or anneal\$6) near16 (osf or oisf or stacking near2 fault) near10 (hydrogen or argon or inert)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/07 15:51
S25	31	(si or silicon) near5 wafer same (heat near2 treat\$6 or anneal\$6) near16 (void) near10 (hydrogen or argon or inert)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/07 16:01
S26	73	(si or silicon) near5 wafer same void near5 size	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/07 16:18

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S27	3	"20050211158"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/07 16:25
S28	78	"1137069"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/07 17:24
S29	1	"01137069"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/07 16:26
S30	2	"11037069"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/07 16:26
S31	4	czochralski same carrier near2 gas near16 exhaust	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/07 17:25
S32	6	czochralski and carrier near2 gas near16 exhaust	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/07 17:27
S33	343	czochralski and exhaust	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/07 17:27
S34	77	czochralski and exhaust near17 inlet	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/07 17:28
S35	25	czochralski and exhaust near17 inlet and heat near2 shield\$7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/07 17:30
S36	26176	czochralski and exhaust near17 purg\$6and heat near2 shield\$7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/07 17:30

S37	4	czochralski and exhaust near17 purg\$6 and heat near2 shield\$7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/07 17:30
S38	36	czochralski and heat near2 shield\$7 near15 adjust\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/07 17:31
S39	27	(US-20060016387-\$ or US-20030209186-\$ or US-20030047130-\$ or US-20020121238-\$ or US-20050268840-\$ or US-20020144641-\$ or US-20020179003-\$ or US-20020179006-\$ or US-20030041796-\$ or US-20030041796-\$ or US-20050250297-\$ or US-20050211158-\$).did. or (US-6458204-\$ or US-6179910-\$ or US-6188090-\$ or US-7204881-\$ or US-7226505-\$ or US-7204881-\$ or US-6146911-\$ or US-680260-\$ or US-6315828-\$).did. or (EP-1137069-\$).did. or (US-20030029375-\$ or JP-2002128593-\$).did. or (US-20030029375-\$ or JP-2000109395-\$ or US-5443034-\$). did.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/06/08 09:53
S40	5	S39 and convex	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/08 09:55
S41	6	S39 and cooler	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/08 10:04
S42	15	heat near2 shield near16 cooler and czochralski	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR,	ON	2007/06/08 10:09

S43	2	"200031325"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/08 10:21
S44	32	czochralski and cooler near16 (gradient near2 (temperature or thermal))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/08 10:32
S45	1	"6458204".pn. and temperature near2 gradient	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/08 10:54
S46	14	S39 and oxygen near5 concentration	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/08 10:54
S47	5	S39 and carbon near6 concentration	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/08 13:41